

AS S4 14. (Twice Amended) A circuit board on which is mounted the semiconductor device as defined in claim 8.

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REMARKS

Claims 8-12, 14 and 15 are pending, with non-elected claims 1-7 being withdrawn from consideration by the January 16, 2001 Response to Restriction Requirement and claim 13 being canceled herein. Reconsideration of the application in view of the foregoing amendments and the following remarks is respectfully requested.

I. FORMAL MATTERS

A. The Office Action objects to the drawings because reference characters "34" and "36" have been used to designate solder balls. Please see the attached Request for Approval of Drawing Corrections wherein the reference "34" has been removed from Figure 1D. Accordingly, in view of the Request for Approval of Drawing Corrections, the Applicant respectfully requests withdrawal of the objection.

B. The Office Action rejects claim 11 under 35 U.S.C. §112, second paragraph, due to a lack of antecedent basis. In response, the Applicant has amended claim 11 to recite that the "anisotropic conductive material is provided to cover said interconnect pattern in its entirety." Accordingly, in view of this amendment, Applicant respectfully requests withdrawal of the rejection.

II. CLAIMS 8-15 DEFINE PATENTABLE SUBJECT MATTER

The Office Action rejects claims 8-15 under 35 U.S.C. §102(e) as being unpatentable over U.S. Patent 5,783,465 to Canning. This rejection is respectfully traversed.

The Office Action asserts that Canning discloses all of the features of the claimed invention. However, it is respectfully submitted that Canning does not disclose an adhesive that is interposed between a surface of said substrate on which the interconnect pattern is

formed and a surface of said semiconductor chip on which said electrodes are formed, so as to cover at least part of a lateral surface of the semiconductor chip, as claimed in claim 8.

That is, as shown in Figure 5B, lateral surface 28 is covered with an adhesive substance. It is respectfully submitted that Canning does not disclose such features.

Canning discloses, in Figures 1 and 2, that the adhesive 15 is placed between the component assembly 13 and substrate 11. Nowhere does Canning teach, disclose or suggest a lateral surface of a semiconductor chip having an adhesive that covers at least part of the lateral surface.

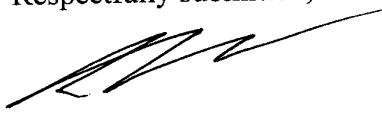
In view of the foregoing remarks, it is respectfully submitted that Canning does not disclose the features of claims 8-12, 14, and 15. Accordingly, withdrawal of the rejection under 35 U.S.C. §102(e) is respectfully requested.

III. CONCLUSION

In view of the foregoing amendments and remarks, Applicant respectfully submits that claims 8-12, 14 and 15 are now in condition for allowance.

Should the Examiner believe that anything further would be desirable in order to place this application in better condition for allowance, the Examiner is invited to contact Applicant's undersigned representative at the telephone number listed below.

Respectfully submitted,



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JAO:CCH/mdw

Attachments:

Appendix
Request for Approval of Drawing Correction

Date: May 29, 2001

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Alexandria, Virginia 22320
Telephone: (703) 836-6400

<p>DEPOSIT ACCOUNT USE AUTHORIZATION Please grant any extension necessary for entry; Charge any fee due to our Deposit Account No. 15-0461</p>
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APPENDIX

Changes to Claims:

Claim 13 is canceled.

Please amend claim 11 as follows:

11. (Amended) The semiconductor device as defined in claim 10, wherein said anisotropic conductive material is provided to cover ~~the whole of~~ said interconnect pattern in its entirety.

14. (Twice Amended) A circuit board on which is mounted the semiconductor device as defined in claim 48.